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| Type Document  | Product Specification | Revised /Edition | H                               |
| Date Issued  | 2003/10/28            | Data Revised     | 2020/12/21                      |
| Subject: JS-1173-XX JS-1173-T JS-1173-TP JS-1174-XXXXXX JS-1174R-XXXX<br>Pitch 1.50mm DIP Series Wire to Board Connector |                       |                  | Issued By:<br>Engineering Dept. |

*This specification is referred to 1.50mm DIP series wire to board connector.*

本規格書內容係提供 1.50 mm DIP 系列產品相關參考，

其用途為電線端相接於電路板端連接器

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| REV. (版次) | Revision Record (改版變更原因)   | Date(日期)   | ECN No.       |
|-----------|--|------------|---------------|
| B         | 增加中文敘述 以及增加版次變更註記欄   | 2010/01/14 | EC2010-01-021 |
| C         | 鹽水噴霧週期以電鍍方式區隔為 8 小時與48 小時；   | 2011/05/05 | EC2011-05-009 |
| D         | 1.增加耐久性 及溫升 2.刪除硫化氫 3.修正(EIA-364) 參考規範<br>2.依據CSA C22.2 No.182.3 修訂6.2 項 Wire Pullout Force(Axial)<br>3 增列Wave Peak Soldering In- Process Temperature Profile<br>4.Solder Ability 附註Tin Plated : 95% / Gold Plated : 75% | 2013/10/28 | EC2013-10-028 |
| E         | 1增訂3.5項Storage of Package以及 3.6 項Floor Life<br>2增訂8.4項Cold(Low Temperature)耐寒試驗 , EIA-364-59A  | 2014/07/14 | EC2014-07-014 |
| F         | 1.修訂Wave Peak Soldering In- Process Temperature Profile<br>2.增訂2.0項 66V0 with Glass Fiber  | 2014/11/25 | EC2014-11-025 |
| G         | 1 增訂 8.8 項 Salt Spray 鹽水噴霧 2 修正 8.9 項 Solder Ability 焊錫性 3.刪除 BSI 標示   | 2017/06/09 | EC2017-06-009 |
| H         | Delete 8.10 NY66+G.F.適用 265 度溫度曲線  | 2020/12/21 | EC2020-12-018 |



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| <b>Pitch 1.50mm DIP Series Wire to Board Connector</b>                       |                              |                         |   |

**1.0 Product Name/Part Number & Drawing Number(產品名稱 / 產品型號及圖面型號):** Note: (xx) The number of the circuits.

| Product Name(產品名稱) |                  | Part Number(零件型號)                              | Drawing Number(圖面型號) |
|--------------------|------------------|--|----------------------|
| Crimp Terminal     |                  | JS-1173-T (Stamping after tin plated ; 先電鍍後沖壓) |                      |
|                    |                  | JS-1173-TP (Stamping before Plated ; 先衝壓後電鍍)   |                      |
| Housing            |                  | JS-1173-XX                                     |                      |
| Wafer              | Straight(直立式)    | JS-1174-XX(PANM) JS-1174-XX(PANXX)             |                      |
|                    |                  | JS-1174-XX(XXXM) JS-1174-XX(XXXXX)             |                      |
|                    | Right Angle (臥式) | JS-1174R-XX(XXM) JS-1174R-XX(XXXX)             |                      |
|                    |                  | JS-1174R-XX(D1M) JS-1174R-XX(D1XX)             |                      |
|                    |                  | JS-1174R-XX(D5M) JS-1174R-XX(D5XX)             |                      |

**2.0 Construction/Dimensions/Material & Surface Finish(材質以及表面鍍層):**

| Part Name(零件名稱)        |                        | Material(材質)             | Surface Finish(表面鍍層) |
|------------------------|------------------------|--------------------------|----------------------|
| Crimp Terminal ( 柳壓端子) |                        | Phosphor Bronze          | Tin-Plated           |
| Housing (電線端連接器)       |                        | Nylon 66                 | UL 94V-0             |
| Wafer<br>(電路板端連接器)     | Circular Pin<br>(圓型導體) | Brass                    | Blank : Tin Plated   |
|                        |                        |                          | M : Matte-Tin Plated |
|                        | Base(膠座)               | Nylon 46                 | UL 94V-0             |
| Nylon 66               |                        |                          | UL 94V-0             |
|                        |                        | Nylon66 with Glass Fiber | UL 94V-0             |

**3.0 Characteristic(產品特性):**

| Item(項目) |  | Standard(標準規範)  |  |
|----------|--|---|--|
| 3.1      | 額定電流 Rated Current                     | 1 A AC/DC   |  |
| 3.2      | 額定電壓 Rated Voltage                     | 50 V AC/DC  |  |
| 3.3      | Ambient Temperature Range<br>環境與操作溫度範圍 | (操作使用溫度與濕度範圍) Operating Temp. : -25°C~+85°C ; 85% R.H. Max<br>Including 30°C Terminal Temperature Rise at rated Current ,<br>(包括定額電流內，端子所產生 30°C以下溫昇) |  |
| 3.4      | Applicable Wire 適用電線                   | 3.4.1   | (金屬導體之型號) Conductor Construction Size: AWG #28~#32                 |
|          |  | 3.4.2   | (電線絕緣材質外徑) Wire Insulation O.D.: 0.5mm~0.9mm                       |
| 3.5      | Storage of Package<br>包裝未拆封之保存         | Temperature and Humidity Condition<br>溫濕度條件   | Temperature 溫度 : -10°C~+40°C<br>Percentage Humidity 相對濕度: 70 % Max |
|          |  | Term 保存期限   | Housing<br>2 Years<br>Crimp Terminal & Wafer<br>1 Year             |
| 3.6      | Floor Life 拆封後使用期限                     | Wafer & Crimp Terminal  | 3 Months   |



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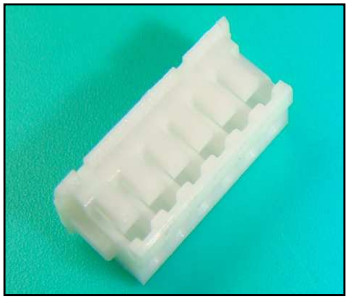
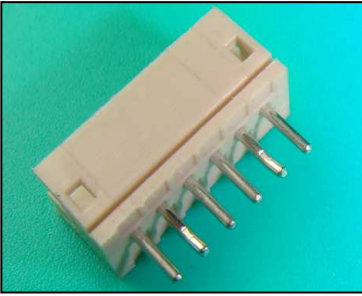
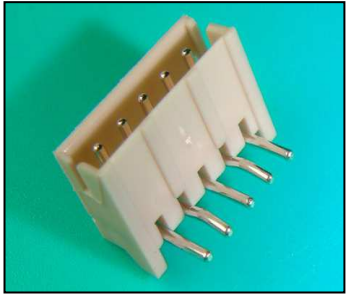
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Note: 適用電路板厚度 Applicable Printed Circuit Board Thickness: 0.6~1.2mm , 1.6 mm

**4.0 Specimen(樣本圖示):**

| Part Name / Part Number / Picture or Photograph 零件名稱 / 零件型號 / 樣本圖示 |  |   |  |
|--|--|---|--|
| <b>Crimp Terminal</b><br><br>JS-1173-T<br><br>JS-1173-TP           |   | <b>Housing</b><br><br>JS-1173-XX                              |   |
| <b>Wafer</b><br><br><b>Straight</b><br><br>JS-1174-XXXXXX          |  | <b>Wafer</b><br><br><b>Right Angle</b><br><br>JS-1174R-XXXXXX |  |

**5.0 Applicable Standards(適用規範):**

ANSI/EIA 364 ; EIA/ECA 364 Testing method for electrical connectors. 電子連接器 所適用之 ANSI/EIA 364 ; EIA/ECA 364 測試規範

**6.0 Mechanical Performance(機械性能):**

| Item(項目) |   | Test Condition(測試條件)   | Requirement(規格)                                 |
|----------|---|--|---|
| 6.1      | <b>Insertion &amp; Withdrawal Force</b><br>嵌入力與拔出力                  | Insert and withdrawal with connectors at the speed rate of $25.4 \pm 3$ mm /minute. 連接器兩端勘合，以每一分鐘 $25.4 \pm 3$ mm的速率，作嵌入與拔出往返測試 (EIA/ECA 364-13D)<br><b>( Excluding Plastic Detents不包含膠座卡榫結合力)</b> | Refer to 9.1 Table1.<br>參照第 9.1 項 表格 1          |
| 6.2      | <b>Wire Pullout Force(Axial)</b><br>電線脫離端子包覆之拔出力(軸向)                | Pull out the cable from contact terminal at the speed rate of $25.4 \pm 3$ mm/minute. 對端子所包覆電線，施以每一分鐘 $25.4 \pm 3$ mm 速率之軸向拔出力 CSA C22.2 No.182.3  | <b>AWG#28 size wire 0.91kgf/Min. (8.9N 牛頓)</b>  |
|          |   |  | <b>AWG#30 size wire 0.46kgf/Min. (4.4N 牛頓)</b>  |
|          |   |  | <b>AWG#32 size wire 0.23kgf/Min. (2.2N 牛頓)</b>  |
| 6.3      | <b>Crimp Terminal Retention Force ( in Housing )</b><br>鍍線端子與膠座間保持力 | Axial pullout force on the terminal in the housing at the speed rate of $25.4 \pm 3$ mm per minute. 對於已經存在於膠座當中鍍線端子，施以每一分鐘 $25.4 \pm 3$ mm 速率之軸向拔出力 (EIA/ 364-05)                                  | 單一接觸點 Per Contact<br>最小容許值 <b>0.70 kgf/Min.</b> |



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| Item(項目)   | Test Condition(測試條件)   | Requirement(規格)                          |
|--|--|--|
| 6.4<br>Circular Pin Retention Force ( in Base )<br>圓型針與膠座之間保持力 | Axial pullout force on the circular pin in the base at the speed rate of 25.4 ± 3 mm per minute. (EIA 364-29C)<br>對於已經存在於膠座當中圓型針，施以每一分鐘 25.4 ± 3 mm 速率之軸向拔出力 | 單一接觸點 Per Contact<br>最小容許值 0.70 kgf/Min. |

7.0 Electrical Performance(電氣性能) :

| Item(項目)  | Test Condition(測試條件)  | Requirement(規格)  |
|---|---|--|
| 7.1<br>(Low –Signal Level)<br>Contact Resistance<br>(低階信號) 接觸阻抗 | A maximum voltage of 20mV and a maximum current of 10mA are applied to the mate connector. 對組合狀態下連接器，於其兩端施以最大測試電壓 20mV 以及最大測試電流 10mA (EIA/ECA 364-23C)<br>( Does not include wire resistance 不包含電線阻抗 )                          | Contact Resistance:<br><b>20 milliohms Max.</b><br>最大容許值. 20 毫歐姆           |
| 7.2<br>Insulation Resistance<br>絕緣阻抗                            | Apply 500V D/C for 1 minute between adjacent contacts to measure the insulation resistance. 對相鄰兩接觸導體，於一分鐘時間內施予 500V D/C 電壓，並量測其間絕緣阻抗值 (EIA 364-21C)   | Insulation Resistance:<br><b>Initial 500 megohms Min</b><br>最初容許值. 500 兆歐姆 |
| 7.3<br>Withstanding Voltage<br>耐電壓                              | Apply 500 A/C (rms) for 1 minute and the leakage current shall not exceed 0.5mA to the adjacent contacts and ground of the mate connectors. (EIA 364-20C)<br>對組合狀態下連接器，於其相鄰兩導體末端各施以電壓 500 A/C (實效值) 時間 1 分鐘，且漏電流必須小於 0.5mA(毫安培) | No breakdown or flashover.<br>無損毀或者產生火花                                    |

8.0 Environmental Performance(環境性能) :

| Item(項目)                 | Test Condition(測試條件)   | Requirement(規格)   |
|--------------------------|--|---|
| 8.1<br>Durability<br>耐久性 | Mate Connectors up 50 Cycles at a Maximun rate of 10 cycles Per minute prior to environmental test 以組合狀態下連接器且未經環境測試，依每分鐘內進行10次嵌入與拔出之最大速率，連續50次嵌入與拔出往返測試 (EIA/ECA 364-09C ) | (After the test)<br>Contact resistance :<br><b>30 mΩ Max</b><br>經耐久性試驗後接觸阻抗 :<br>最大容許值 30 毫歐姆 |



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| Item(項目) |   | Test Condition(測試條件)  | Requirement(規格)  |
|----------|---|---|--|
| 8.2      | <b>Temperature Rise</b><br><b>(Via Current Cycling)</b><br>溫度上昇<br>(經由電流循環操作) | <b>Mate connector . measure the temperature rise of contact when the maximum rated current is passed</b><br>以組合狀態下連接器，通過最大容許電流量測其導體溫度上昇值<br><b>(EIA 364-70B Conditions 1 . Method 1)</b>  | <b>Mate connectors</b><br><b>Temperature Rise:</b><br><b>+30°C/Max.</b><br>組合狀態下之連接器溫度<br>上昇最大容許值+30°C   |
| 8.3      | <b>Vibration</b><br>耐振動   | <b>A mated connector shall be mounted on a printed Circuit board and subjected to a vibration test of the following conditions. During the test, test current continuity shall be checked. After the test, contact resistance shall be measured.</b><br>以組合狀態下連接器焊接於電路板作為試驗樣品,依照隨附如下規格要求,進行耐振動試驗，試驗過程中確認是否產生不連續電流(斷電)現象，並於試驗過後量測其接觸阻抗。<br><b>(EIA/ECA 364-28E-Condition 1)</b><br><b>Frequency(頻率) : 10~55~10 Hz/minute.</b><br><b>Amplitude (振幅) : 1.5 mm P-P</b><br><b>Direction (方向) :1. Axis of up and down.上下軸向(Y 軸)</b><br><b>2. Axis of right the left. 左右軸向(X 軸)</b><br><b>3. Axis of front and back.前後軸向(Z 軸)</b><br><b>Period(週期) : 2 hours for each direction.</b><br>(每一個軸向持續 2 小時) | <b>Initial Contact Resistance :</b><br><b>20 milliohms Max.</b><br>接觸阻抗最初容許值 20 毫歐姆<br><b>(After the test)</b><br><b>Contact Resistance:</b><br><b>30 milliohms Max.</b><br>經耐振動試驗後接觸阻抗<br>最大容許值 30 毫歐姆<br><b>No discontinuity current is longer than 1 microsecond.</b><br>電流中斷現象，<br>時間不可多於 1 微秒 |
| 8.4      | <b>Cold 耐寒試驗</b><br><b>(Low Temperature)</b>                                  | <b>A mated connector shall be placed in a cold chamber of the following conditions. After the test, leave the specimen at room temperature for 1~2 hours before the contact resistance shall be measured. (EIA 364-59A Procedure 4)</b><br>以組合狀態下連接器放置於低溫空間內,依照隨附如下規格要求,進行耐寒試驗，經試驗過後將樣品置於室溫 1~2 小時,再量測其接觸阻抗。<br><b>Temperature(溫度) : -25±3°C.</b><br><b>Period(週期): 96 hours continuously . (持續 96 小時)</b>  | <b>Initial Contact Resistance :</b><br><b>20 milliohms Max.</b><br>接觸阻抗最初容許值 20 毫歐姆<br><b>(After the test)</b><br><b>Contact Resistance :</b><br><b>30 milliohms Max. .</b><br>經耐寒試驗後接觸阻抗<br>最大容許值. 30 毫歐姆   |



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| Item(項目) | Test Condition(測試條件)  | Requirement(規格)  |
|----------|---|--|
| 8.5      | <p style="text-align: center;"><b>Humidity</b><br/>(Steady State)<br/>恆溫恆濕</p> <p>A mated connector shall be placed in a humidity chamber of the following conditions. After the test, leave the specimen at room temperature for 1~2 hours before the contact resistance, the insulation resistance and the dielectric withstanding voltage shall be measured.<br/>(EIA 364-31B Conditions II. Method A)</p> <p>以組合狀態下連接器放置於恆定溫度與濕度的空間，依照隨附如下規格要求，進行恆溫恆濕試驗，經試驗過後將樣品置於室溫 1~2 小時，再量測其接觸阻抗、絕緣阻抗、以及耐電壓測試。</p> <p>Temperature(溫度) : 40±2°C.<br/>Relative Humidity(相對濕度) : 90%~95% (RH).<br/>Period(週期) : 96 hours continuously. (持續 96 小時)</p>  | <p>(After the test)<br/><b>Contact Resistance:</b><br/><b>30 milliohms Max.</b><br/>經恆溫恆濕試驗後接觸阻抗<br/>最大容許值. 30 毫歐姆</p> <p>(After the test)<br/><b>Insulation Resistance :</b><br/><b>300 Megohms Min.</b><br/>經恆溫恆濕試驗後絕緣阻抗<br/>最小容許值. 300 兆歐姆</p> <p>經恆溫恆濕試驗後測耐電壓<br/>(After the test)<br/><b>Withstanding Voltage:</b><br/><b>500V A/C for 1 minute</b></p> |
| 8.6      | <p style="text-align: center;"><b>Thermal Shock</b><br/>冷熱衝擊</p> <p>A mated connector shall be subjected to a thermal shock test of the following conditions. After the test, leave the specimen at room temperature for 1~2 hours before the contact resistance, the insulation resistance and the dielectric withstanding voltage shall be measured.<br/>以組合狀態下連接器作為試驗樣品，依照隨附如下規格要求，進行冷熱衝擊試驗，經試驗過後將樣品置於室溫 1~2 小時，再量測其接觸阻抗、絕緣阻抗、以及耐電壓測試。</p> <p>(EIA/ECA 364-32D Conditions I. Method A)</p> <p>One Cycle Consists Of:<br/><b>-55°C+0/-3°C for 30 minutes. → Room Temp. 5 minutes</b><br/><b>85°C+3/-0°C for 30 minutes. → Room Temp. 5 minutes</b></p> <p>Total Cycles: 5 Cycles.<br/>以 -55°C +0/-3°C 溫度持續 30 分鐘，經室溫 5 分鐘，而後再以 85°C +3/-0°C 溫度持續 30 分鐘，再經室溫 5 分鐘，構成一次冷熱循環，總計循環次數 5 次。</p> | <p style="text-align: center;"><b>Same as paragraph 8.5</b><br/>同 8.5 章節</p>   |





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| <b>Date Issued</b>   | <b>2003/10/28</b>            | <b>Data Revised</b>     | <b>2020/12/21</b> |
| <b>Subject: JS-1173-XX JS-1173-T JS-1173-TP JS-1174-XXXXXX JS-1174R-XXXX</b> |                              |                         | <b>Issued By:</b> |
| <b>Pitch 1.50mm DIP Series Wire to Board Connector</b>                       |                              |                         |                   |

| Item(項目) |                         | Test Condition(測試條件)   | Requirement(規格)   |
|----------|-------------------------|--|---|
| 8.7      | Thermal Aging<br>高溫老化試驗 | <p>A mated connector shall be placed in a heat oven of the following conditions. After the test, leave the specimen at room temperature for 1~2 hours before the contact resistance shall be measured.</p> <p>(EIA 364-17B Conditions 3 . Method A )以組合狀態下連接器放置於加熱烤箱當中, 依照隨附如下規格要求, 進行高溫老化試驗, 經試驗過後將樣品置於室溫 1~2 小時,再量測其接觸阻抗。</p> <p>Temperature(溫度): <b>85±2°C.</b></p> <p>Period(週期): <b>96 hours continuously . (持續 96 小時)</b></p>  | <p>Initial Contact Resistance :<br/><b>20 milliohms Max.</b></p> <p>接觸阻抗最初容許值 <b>20 毫歐姆</b></p> <p>(After the test)</p> <p>Contact Resistance :<br/><b>30 milliohms Max. .</b></p> <p>經高溫老化試驗後接觸阻抗<br/>最大容許值. <b>30 毫歐姆</b></p> |
| 8.8      | Salt Spray<br>鹽水噴霧      | <p>A mated connector shall be subjected to a Salt Spray test of the following conditions. After the test , the specimen shall be washed with running water and dried naturally before the measurement of contact resistance.以組合狀態下連接器作為試驗樣品, 依照隨附如下規格要求, 進行鹽水噴霧試驗, 試驗過後將樣品用清水沖洗並經過自然風乾, 而後量測其接觸阻抗。(EIA 364-26B Conditions B)</p> <p>Density(鹽水密度): <b>5 % in weight. Temperature(溫度): 35±2°C .</b></p> <p>Period(週期): <b>Terminal or contact (Stamping after tin plated for 8 hours ) ; Terminal or contact (Stamping before tin plated for 48 hours) 端子或導體(先電鍍後沖壓 8 小時) ; 端子或導體 (先沖壓後電鍍 48 小時)</b></p> <p>Salt spray test only define the plating area,without plating area (as copper cross section) will not be defined. 鹽水噴霧測試只判定電鍍區域,無電鍍區域(如折斷面裸銅)則不做判定</p> | <p>Initial Contact Resistance :<br/><b>20 milliohms Max.</b></p> <p>接觸阻抗最初容許值 <b>20 毫歐姆</b></p> <p>(After the test)</p> <p>Contact Resistance:<br/><b>30 milliohms Max.</b></p> <p>經鹽水噴霧試驗後接觸阻抗<br/>最大容許值. <b>30 毫歐姆</b></p>    |
| 8.9      | Solder Ability<br>焊錫性   | <p>Fluxed soldering section of header shall be dipped in solder of the following conditions.(EIA 364-52B)</p> <p>將連接器 pin 針基板嵌入端, 接觸熱溶狀錫料, 依照隨附如下規格要求, 進行焊錫性試驗</p> <p>Solder Temperature (焊錫溫度) : <b>245 ± 5°C.</b></p> <p>Immersion Period (沉浸週期) : <b>3±0.5 Seconds</b></p> <p>(操作方式) :零件焊錫位置, 距離導體末端 <b>1.5mm</b></p> <p>Method : <b>1.5mm from circular pin tip</b></p>  | <p>Solder entirely <b>95%</b> of immersed area must show no voids or pinholes.</p> <p>焊料覆蓋面積必須達到 <b>95%</b>, 而且不能產生氣孔或空隙</p>  |



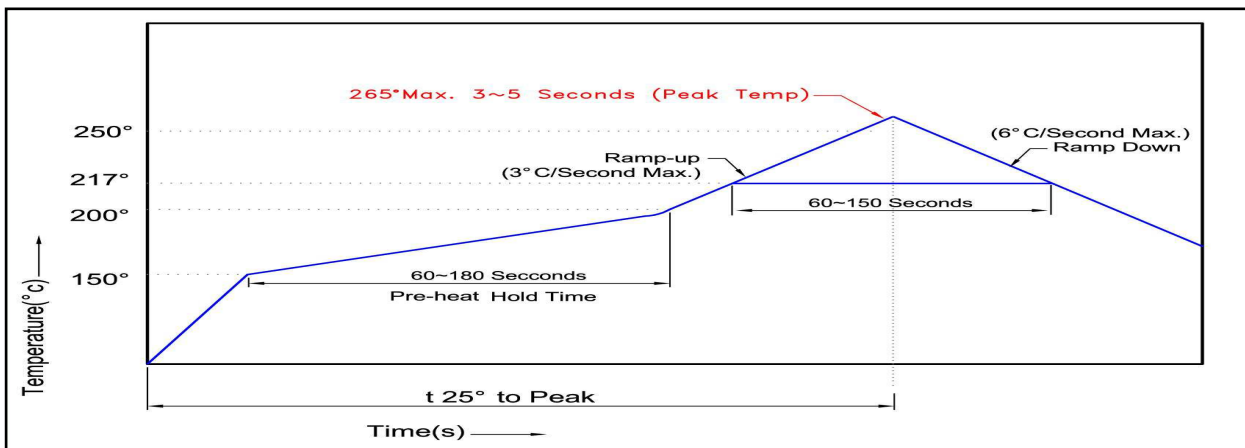
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| <b>Subject: JS-1173-XX JS-1173-T JS-1173-TP JS-1174-XXXXXX JS-1174R-XXXX</b><br><b>Pitch 1.50mm DIP Series Wire to Board Connector</b> |                              |                         | <b>Issued By:</b><br><b>Engineering Dept.</b> |

| Item(項目) | Test Condition(測試條件)  | Requirement(規格)   |
|----------|---|---|
| 8.10     | <p><b>Resistance to Soldering Heat</b><br/>           焊錫耐熱性</p> <p>Resistance to soldering heat when using <b>Nylon 46</b> 使用尼龍 46, 能夠承受焊錫耐熱範圍：<br/>           Refer to Temperature Profile 請參考 8.10.1.1 溫度曲線圖<br/>           (EIA-364-71B)</p> <p>Resistance to soldering heat when using <b>Nylon 66</b> 使用尼龍 66, 能夠承受焊錫耐熱範圍：<br/>           Refer to Temperature Profile 請參考 8.10.1.2 溫度曲線圖</p> <p>By soldering iron 手工烙鐵焊錫適用溫度範圍：<br/> <b>350 ± 5°C 3±0.5 Seconds.</b><br/>           (操作方式)：件焊錫位置，距離導體末端 1.5mm<br/> <b>Method : 1.5mm from circular pin tip</b><br/>           (EIA/ECA 364-56C Procedure 3. Conditions A)</p> | <p><b>No deformation or damage.</b><br/>           不可有變形或損壞</p> |

Notes : Flowing Mixed Gas (EIA 364-65A) shall be conduct by Customer request 混合流動氣體測試遵照客戶需求

**8.10.1 Temperature Profile(溫度曲線圖) :**

**8.10.1.1 Wave Peak Soldering In-Lead Free Process 波峰焊無鉛制程**

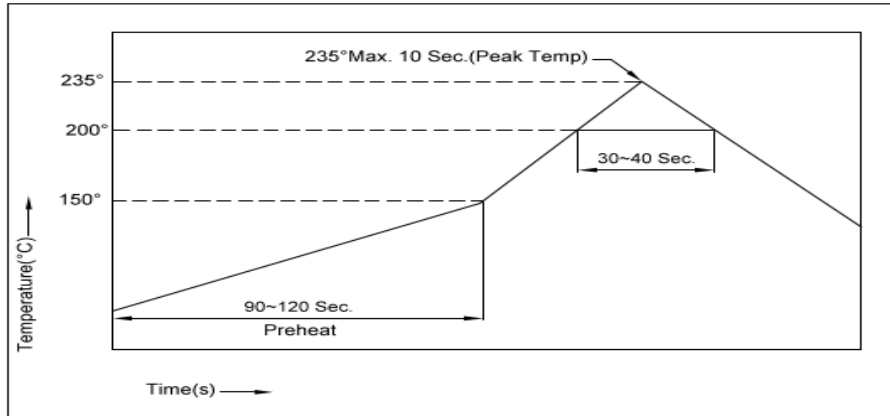






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**8.10.1.2 Wave Peak Soldering In- General Process 波峰焊一般制程**



**9.0 Tables & Attachments**

**9.1 Table 1. Insertion Force (I.F.) & Withdrawal Force (W.F.) for user reference:**

| No. of Circuits<br>極數 | AT INITIAL<br>首次嵌入與拔出(初始值) |                   | AT 50 <sup>TH</sup><br>50 次嵌入與拔出之後 | No. of Circuits<br>極數 | AT INITIAL<br>首次嵌入與拔出(初始值) |                   | AT 50 <sup>TH</sup><br>50 次嵌入與拔出之後 |
|-----------------------|----------------------------|-------------------|------------------------------------|-----------------------|----------------------------|-------------------|------------------------------------|
|                       | I.F. (MAX)<br>嵌入力          | W.F. (MIN)<br>拔出力 | W.F. (MIN)<br>拔出力                  |                       | I.F. (MAX)<br>嵌入力          | W.F. (MIN)<br>拔出力 | W.F. (MIN)<br>拔出力                  |
|                       | 02                         | 2.50              | 0.40                               |                       | 0.20                       | 08                | 5.50                               |
| 03                    | 3.00                       | 0.50              | 0.30                               | 09                    | 6.00                       | 0.90              | 0.70                               |
| 04                    | 3.50                       | 0.60              | 0.30                               | 10                    | 6.50                       | 1.00              | 0.80                               |
| 05                    | 4.00                       | 0.70              | 0.40                               | 11                    | 7.00                       | 1.00              | 0.90                               |
| 06                    | 4.50                       | 0.80              | 0.50                               | 12                    | 7.50                       | 1.20              | 1.00                               |
| 07                    | 5.00                       | 0.80              | 0.60                               | 13                    | 8.00                       | 1.20              | 1.10                               |

Unit: Kg/f

**10.Remark(備註) : Any change or revision for the product specification will not be announced in advance.**

Please contact our sales representative for the latest information.

有關規格書內容經變更或改版，如未能夠及時發佈與通知，煩請連絡我司業務人員以提供產品最新資訊

**Reviewed:** Tom Shih **Approved:** Tom Shih **Verified:** Erin Chou